

Electronic Patent Application Fee Transmittal

Application Number:	10677182			
Filing Date:	02-Oct-2003			
Title of Invention:	Method of forming solder resist pattern			
First Named Inventor/Applicant Name:	Jee-Soo Mok			
Filer:	Laura Cruz/Marivick Watson			
Attorney Docket Number:	LEPA121687			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	1201	2	200	400
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				400